



KOREAN PATENT ABSTRACTS(KR)

Document Code:A

(11) Publication No.1020030065924 (43) Publication Date. 20030809

(21) Application No.1020020006005 (22) Application Date. 20020202

(51) IPC Code:

H01L 21/60

(71) Applicant:

MICROSCALE CO., LTD.

(72) Inventor:

ahn, YU SANG

JI, JAE HWAN

KIM, HAK JAE

LEE, JI YEONG

(30) Priority:

(54) Title of Invention

METHOD OF MANUFACTURING FLIP CHIP BUMP IN SEMICONDUCTOR PACKAGE

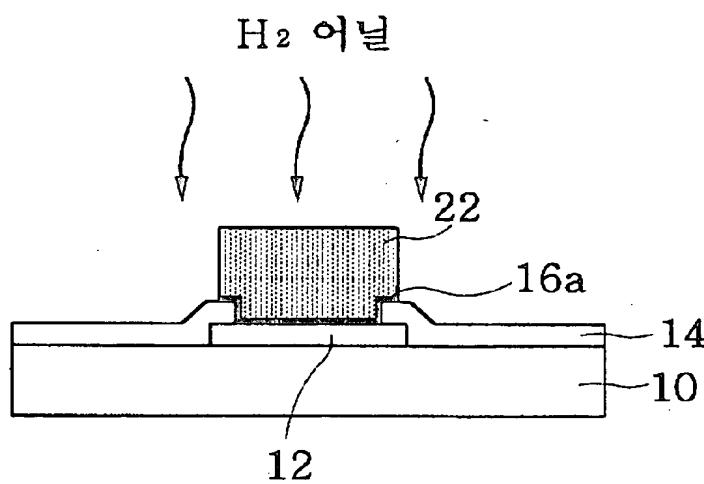
Representative drawing

(57) Abstract:

PURPOSE: A method of manufacturing a flip chip bump in a semiconductor package is provided to improve electrical contact between a probe tip and the surface of a bump in a chip test by removing organic materials on the metal bump with adding H₂ gas in a bump annealing process.

CONSTITUTION: A pad is formed on a semiconductor chip(10). A buffer layer is formed on the chip pad and the semiconductor chip. To expose the pad, the buffer layer is patterned to form an opening portion. An UBM layer(16a) is attached to the pad through the opening portion. A metal bump(22) is formed on the UBM layer. An annealing process is carried out with H₂ gas on the resultant structure.

© KIPO 2003



if display of image is failed, press (F5)

http://patent.kipris.or.kr/bin/Kpa_fulltext.cgi?appl_no=1020020006005

04-02-05